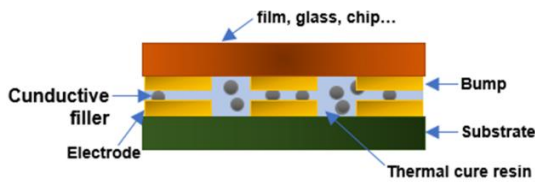


ACP

Screen printing, adhesive to replace SMT

1. Product description

ACP paste is the paste used to attach (F)PCB or part to the PCB on behalf of soldering.



2. Benefits

Anisotropy property

Reduce assembly tact time

Suitable for FOG, COF, COG process



3. Processing

ACP paste is optimized for screen printing process using poly and metal screen mesh.

4. Cleaner

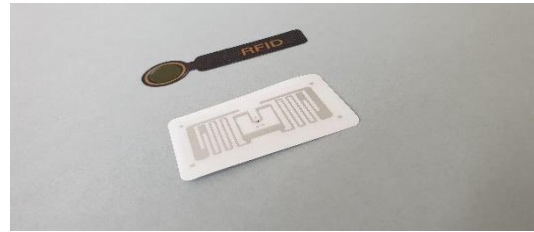
Alcohols, Ketones

5. Curing Condition

Curing at 170°C under suitable pressure and hot pressing process.

6. Storage and shelf life

The paste must be well sealed tightly and stored in a refrigerator of 0 to 10 °C (for ACP-002) and frozen of -20 °C (for ACP-001). Unopened paste is valid for three



months from the manufacturing date. Exhaust used paste as soon as possible, but mixing used and new products is strictly prohibited.

7. Safety and handling

Refer to MSDS for safety and handling information. Leave pastes removed from refrigerator at room temperature for 2 to 3 hours before use. Please exhaust of open products within 7 days.

8. Properties

Items	ACP-001	ACP-002
Binder Type	Urethane acrylate	Epoxy
Solid Contents (wt.%)	5 ~ 12, Ni	20 ~ 30, Ni
Viscosity @ 22°C	30,000 ~ 45,000	80,000 ~ 100,000
Thixotropic Index	1.5 ~ 2.0	1.5 ~ 2.0
Pre-curing Conditions	100 °C, 3min	No needed
Curing Conditions	150 °C, 10min	No needed
Pressure	3.0 ~ 4.0 MPa	0.8 ~ 1.0 MPa
Sheet Resistance	4~5 x 10 ¹² mΩ/□	4~5 x 10 ¹² mΩ/□

9. Environmental test

Test Item	Properties
Thermal Shock	+85°C to -40°C, 30min each, 100 cycles
Dry heat	+85°C, 10 days
Humidity	+85°C, 85%RH, 7 days
Frozen	-40°C

10. Contact

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